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(12) **United States Design Patent**
Walker

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(54) **SPOKED SOLDER PAD**

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(72) Inventor: **Myron Walker**, Redmond, WA (US)

(**) Term: **15 Years**

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(22) Filed: **Feb. 12, 2018**

Related U.S. Application Data

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(51) **LOC (11) Cl.** **15-09**

(52) **U.S. Cl.**
USPC **D15/144**

(58) **Field of Classification Search**
USPC D10/46, 75; D14/435, 436, 437, 438; D15/144, 144.1, 144.2
CPC H01L 24/05; H01L 2224/05555; H01L 2224/05557; H01L 2224/05551; H01L 2224/05563; H05K 1/181; H05K 1/111
See application file for complete search history.

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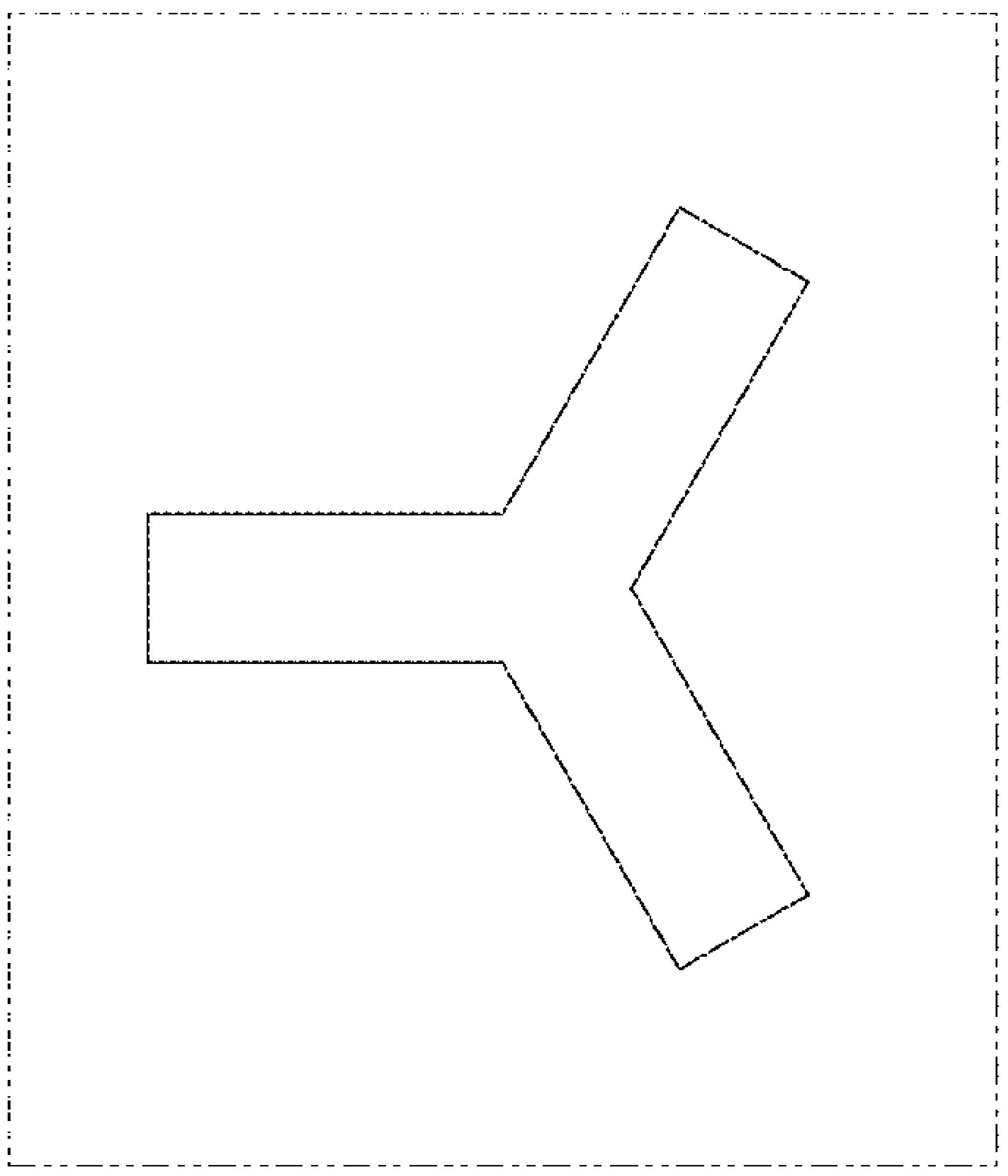
(57) **CLAIM**

The ornamental design for a spoked solder pad, as shown and described.

DESCRIPTION

FIG. **1** is a top plan view of my new design for a solder pad.
FIG. **2** is a top plan view of the solder pad of FIG. **1** with illustrative radial axes drawn.
FIG. **3** is a top plan view of the solder pad of FIG. **1** with illustrative adjacent circuit board traces and vias.
FIG. **4** is a perspective view of the solder pad of FIG. **1** on an illustrative integrated circuit package; and,
FIG. **5** is a perspective view of the solder pad of FIG. **1** on an illustrative circuit board.
Broken line illustrations of environmental structure in the drawings, including the radial axes in FIG. **2**, circuit board traces and vias in FIG. **3**, integrated circuit package outlines in FIG. **4**, and circuit board outlines in FIG. **5**, are provided for illustrative purposes only and form no part of the claimed design.

1 Claim, 5 Drawing Sheets



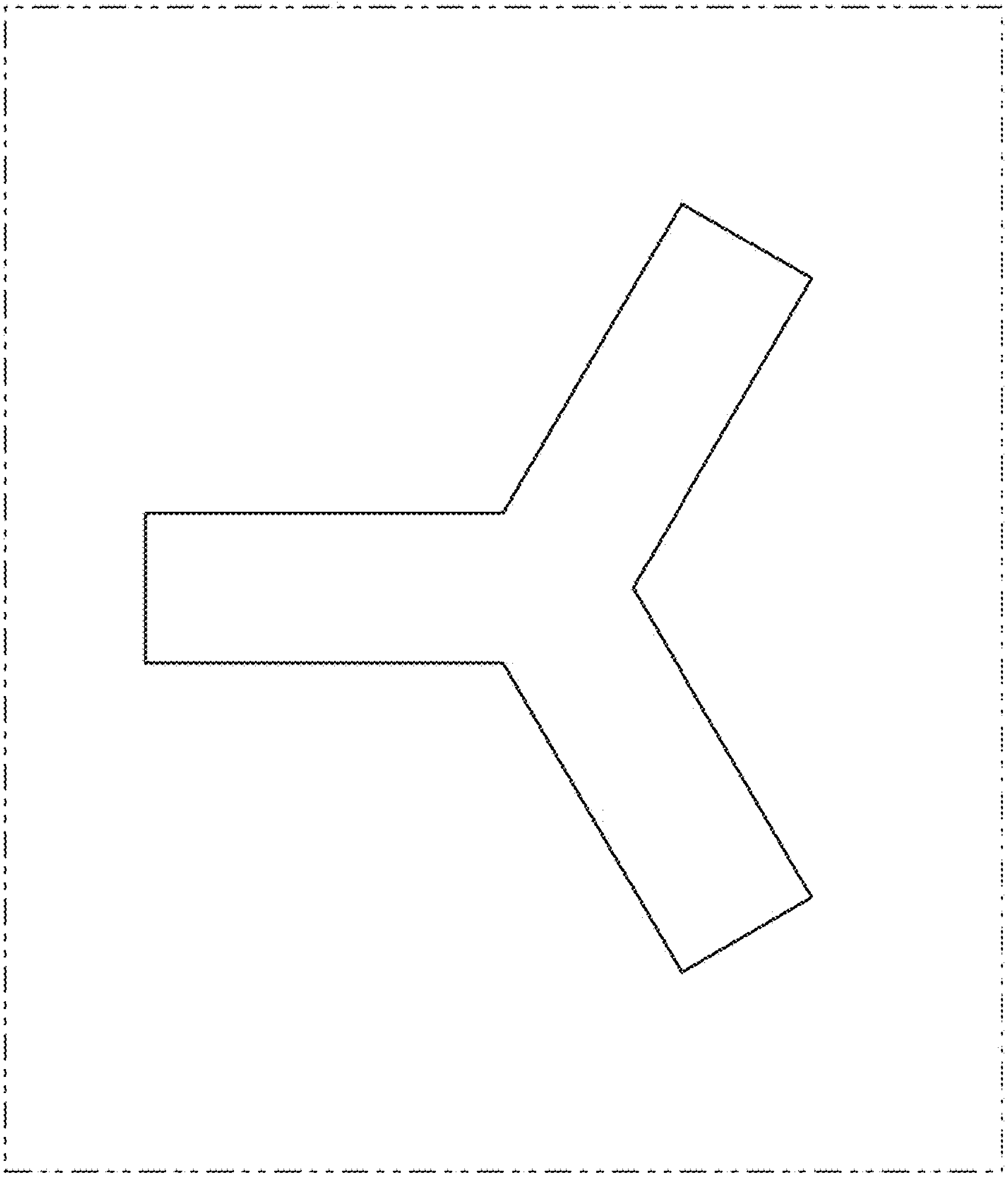


FIG. 1

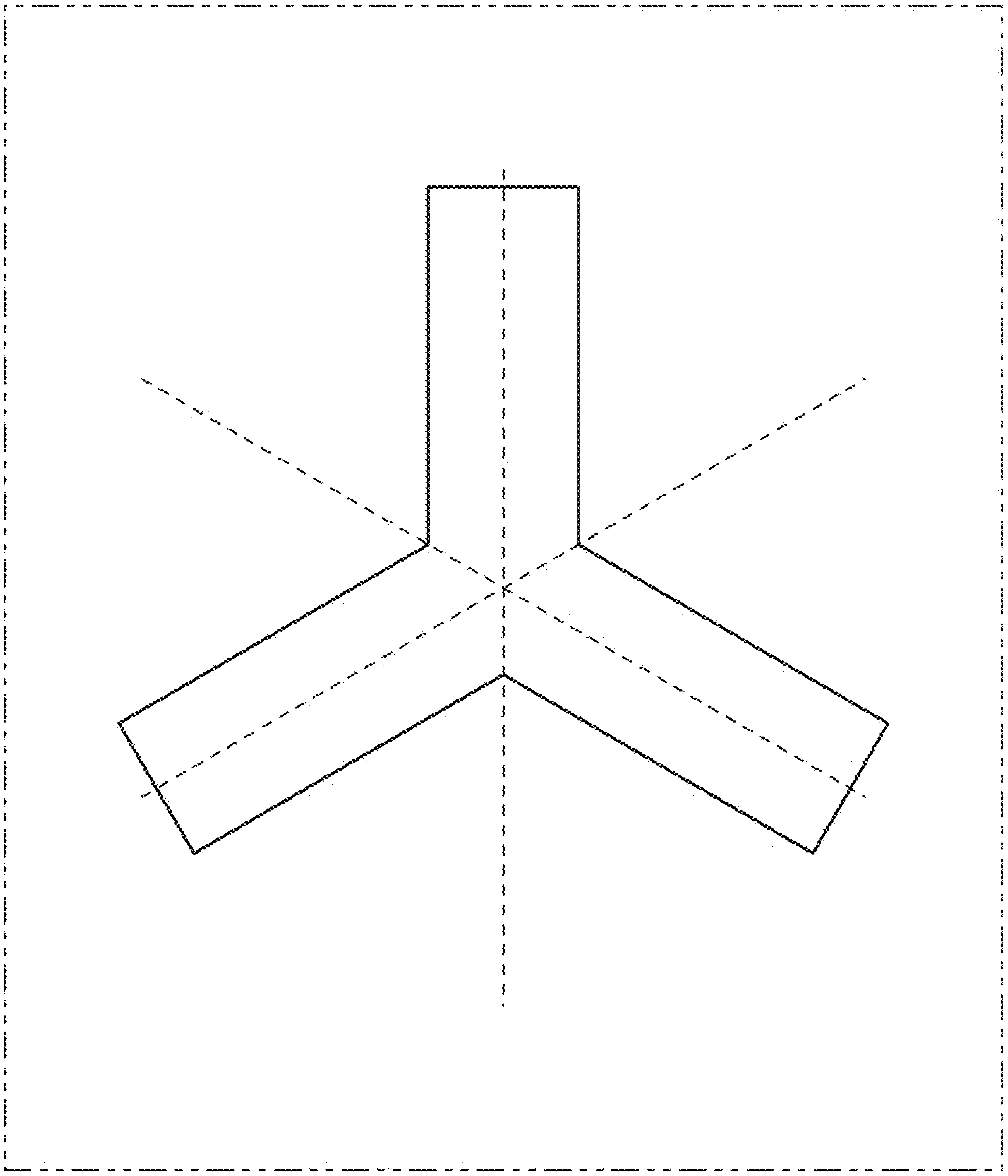


FIG. 2

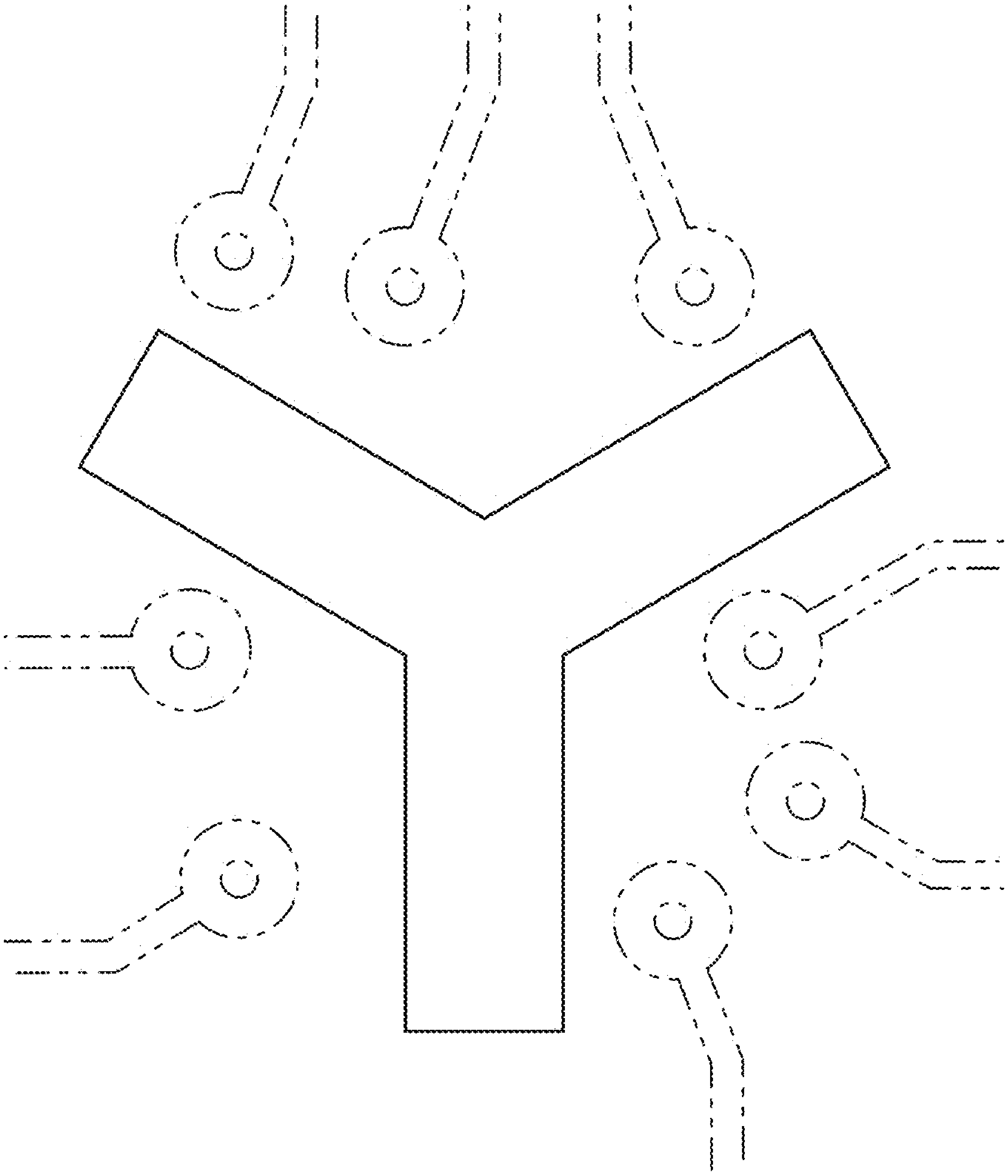


FIG. 3

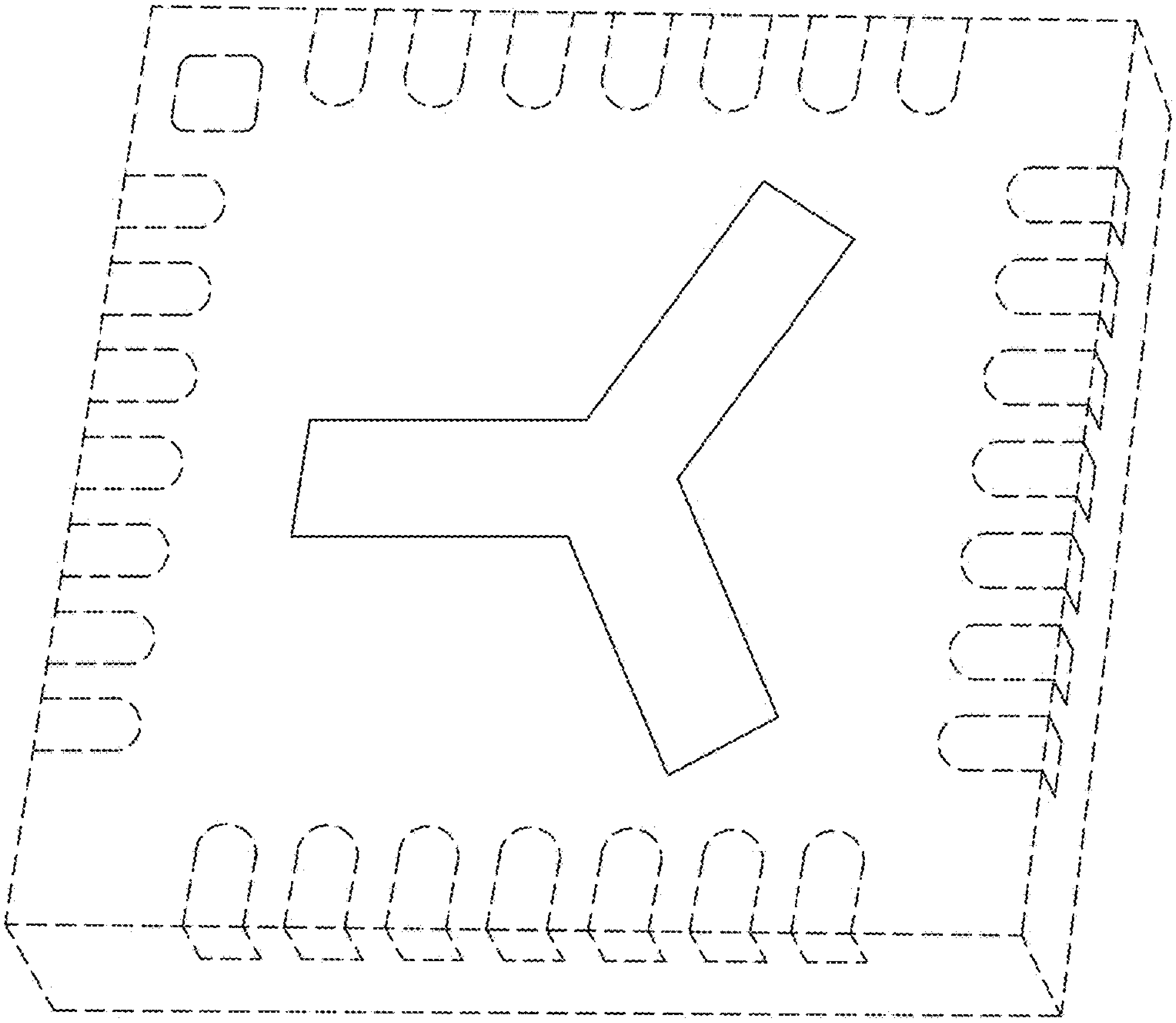


FIG. 4

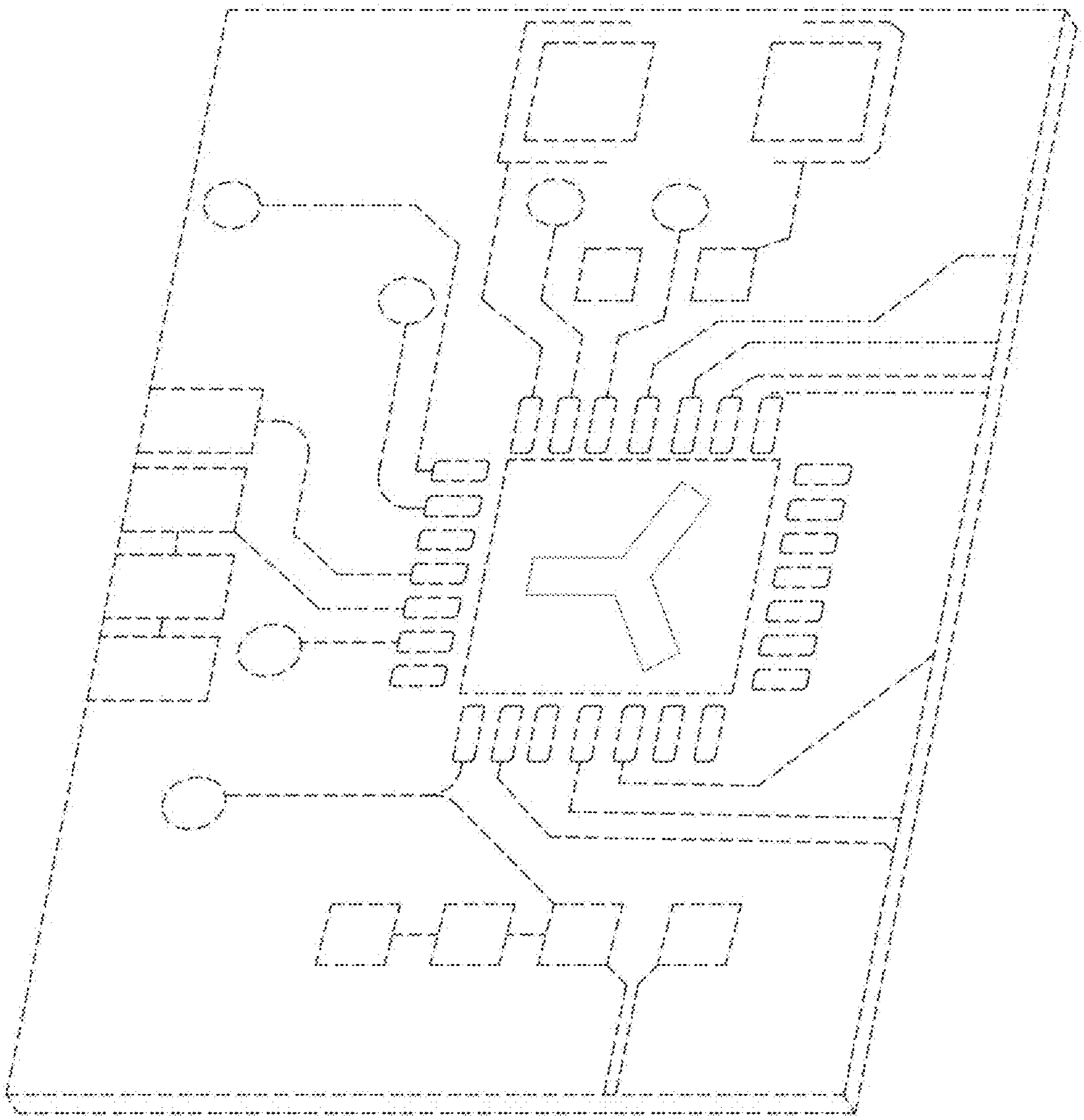


FIG. 5